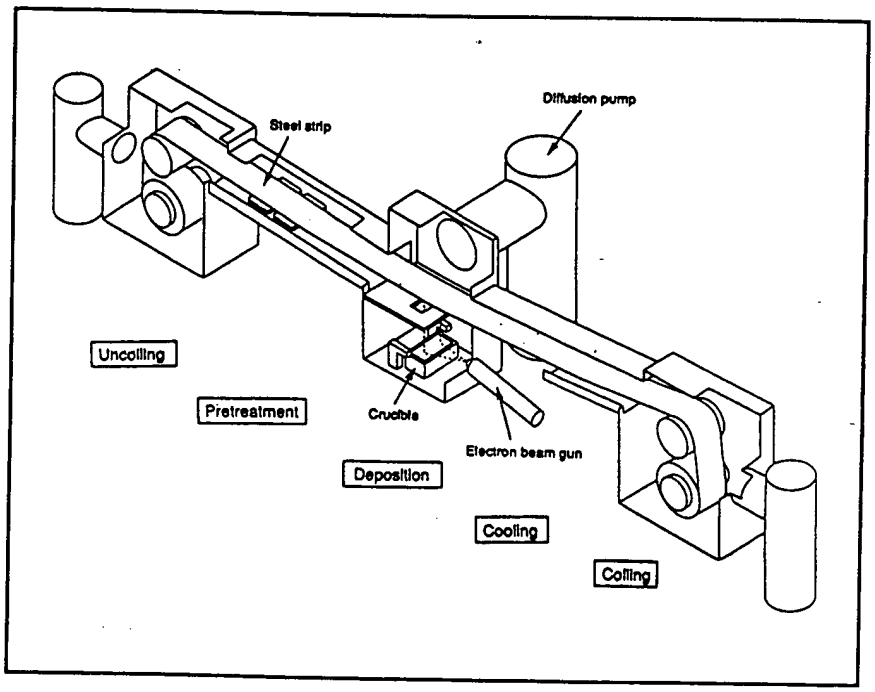
HANDBOOK OF DEPOSITION TECHNOLOGIES FOR FILMS AND COATINGS

Science, Technology and Applications

Second Edition



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